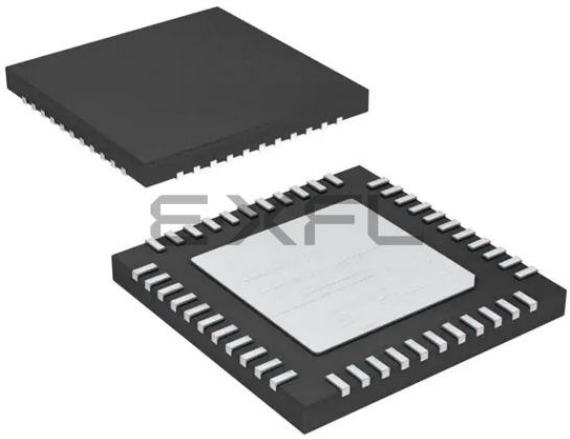
Microchip Technology - PIC24HJ16GP304T-I/ML Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	35
Program Memory Size	16KB (5.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 13x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24hj16gp304t-i-ml

2.7 Oscillator Value Conditions on Device Start-up

If the PLL of the target device is enabled and configured for the device start-up oscillator, the maximum oscillator source frequency must be limited to ≤ 8 MHz for start-up with PLL enabled. This means that if the external oscillator frequency is outside this range, the application must start-up in FRC mode first. The default PLL settings after a POR with an oscillator frequency outside this range will violate the device operating speed.

Once the device powers up, the application firmware can initialize the PLL SFRs, CLKDIV and PLLDBF to a suitable value, and then perform a clock switch to the Oscillator + PLL clock source. Note that clock switching must be enabled in the device Configuration word.

2.8 Configuration of Analog and Digital Pins During ICSP Operations

If MPLAB ICD 3 or MPLAB REAL ICE in-circuit emulator is selected as a debugger, it automatically initializes all of the A/D input pins (ANx) as “digital” pins, by setting all bits in the AD1PCFGL registers.

The bits in the registers that correspond to the A/D pins that are initialized by MPLAB ICD 3 or MPLAB REAL ICE in-circuit emulator, must not be cleared by the user application firmware; otherwise, communication errors will result between the debugger and the device.

If your application needs to use certain A/D pins as analog input pins during the debug session, the user application must clear the corresponding bits in the AD1PCFGL register during initialization of the ADC module.

When the MPLAB ICD 3 or MPLAB REAL ICE in-circuit emulator is used as a programmer, the user application firmware must correctly configure the AD1PCFGL register. Automatic initialization of this register is only done during debugger operation. Failure to correctly configure the register(s) will result in all A/D pins being recognized as analog input pins, resulting in the port value being read as a logic ‘0’, which may affect user application functionality.

2.9 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic low state.

Alternatively, connect a 1k to 10k resistor between VSS and the unused pins.

4.0 MEMORY ORGANIZATION

Note: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"dsPIC33F/PIC24H Family Reference Manual"*, **"Section 4. Program Memory"** (DS70202), which is available from the Microchip website (www.microchip.com).

The PIC24HJ32GP202/204 and PIC24HJ16GP304 architecture features separate program and data memory spaces and buses. This architecture also allows the direct access of program memory from the data space during code execution.

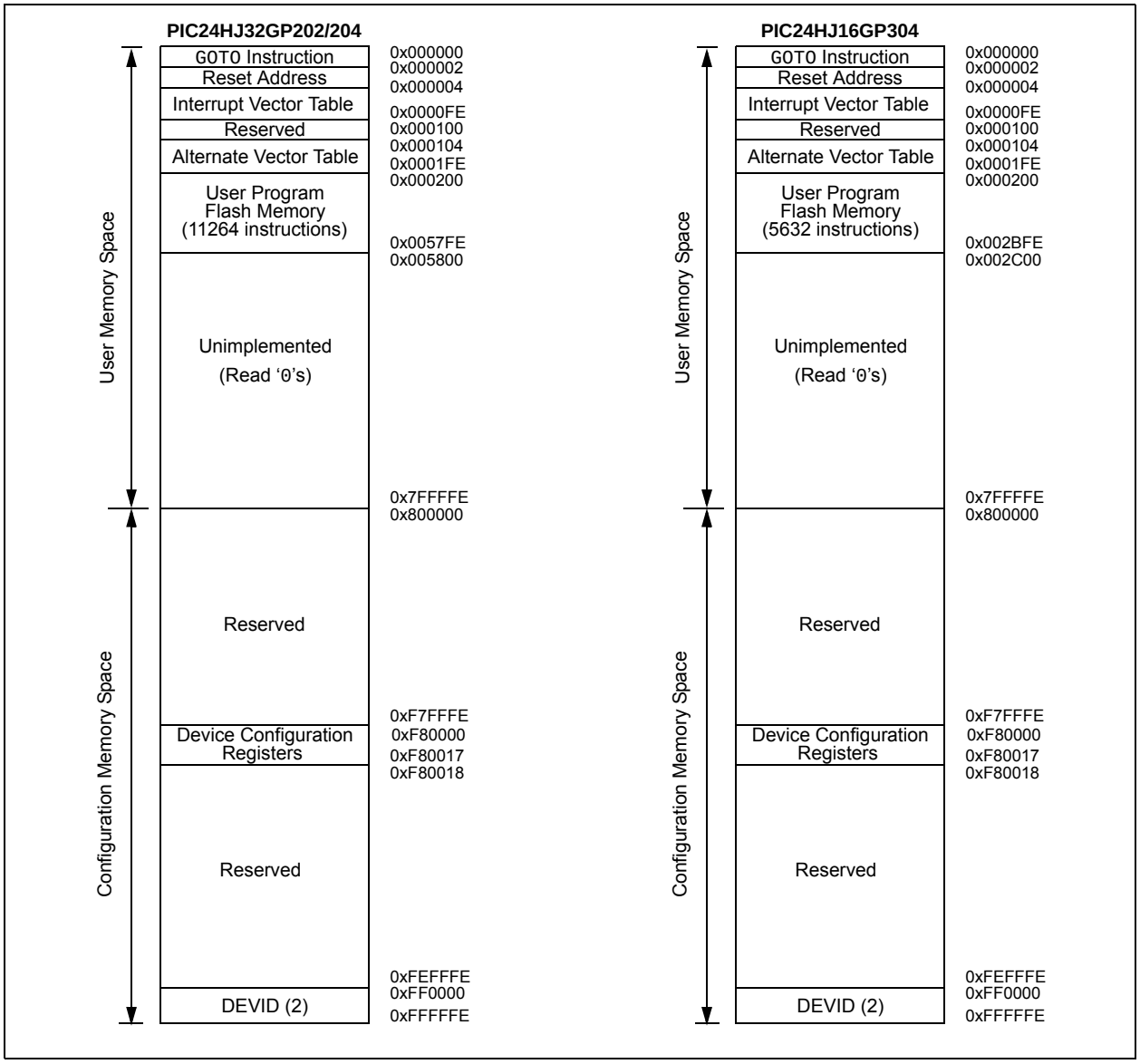
4.1 Program Address Space

The devices program address memory space is 4M instructions. The space is addressable by a 24-bit value derived either from the 23-bit Program Counter (PC) during program execution, or from table operation or data space remapping as described in **Section 4.6 "Interfacing Program and Data Memory Spaces"**.

User application access to the program memory space is restricted to the lower half of the address range (0x000000 to 0x7FFFFF). The exception is the use of TBLRD/TBLWT operations, which use TBLPAG<7> to permit access to the Configuration bits and Device ID sections of the configuration memory space.

The memory maps for the PIC24HJ32GP202/204 and PIC24HJ16GP304 devices are shown in Figure 4-1.

FIGURE 4-1: PROGRAM MEMORY FOR PIC24HJ32GP202/204 AND PIC24HJ16GP304 DEVICES



5.0 FLASH PROGRAM MEMORY

Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Section 4. Program Memory"** (DS70202) of the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip website (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The PIC24HJ32GP202/204 and PIC24HJ16GP304 devices contain internal Flash program memory to store and execute application code. The memory is readable, writable and erasable during normal operation over the entire VDD range.

Flash memory can be programmed in two ways:

- In-Circuit Serial Programming™ (ICSP™) programming capability
- Run-Time Self-Programming (RTSP)

ICSP allows a device to be serially programmed while in the end application circuit. This is done with two lines for programming clock and programming data (one of the alternate programming pin pairs: PGECx/PGEDx), and three other lines for power (VDD), ground (VSS) and Master Clear ($\overline{MCLR}$). This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

RTSP is accomplished using TBLRD (table read) and TBLWT (table write) instructions. With RTSP, the user application can write program memory data either in 'blocks' or 'rows' of 64 instructions (192 bytes) at a time or a single program memory word, and erase program memory in blocks or 'pages' of 512 instructions (1536 bytes) at a time.

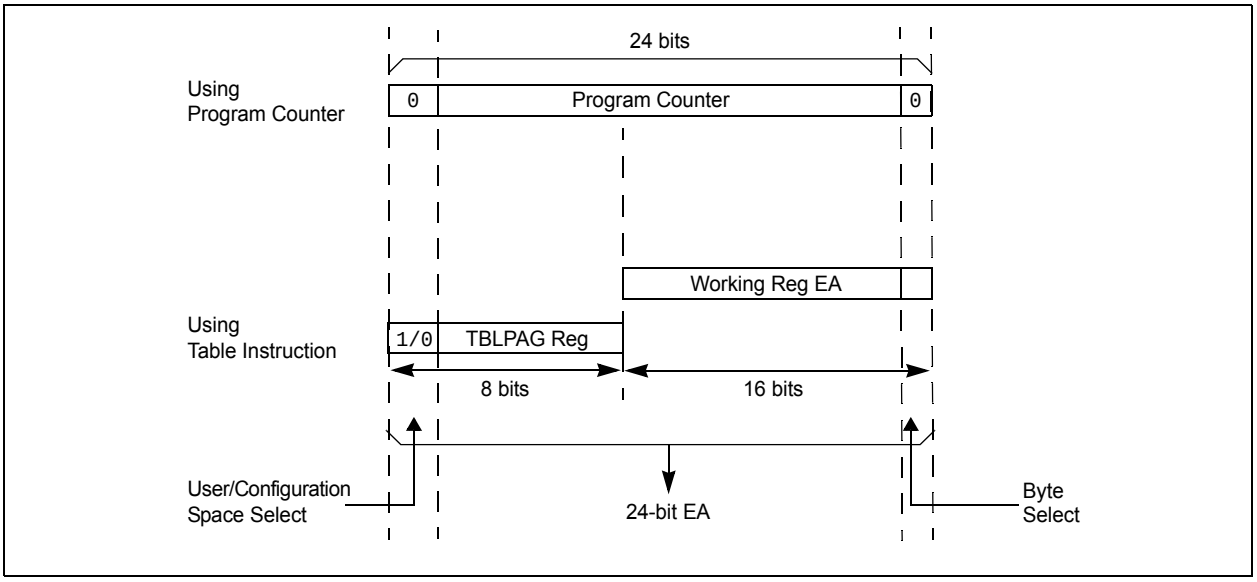
5.1 Table Instructions and Flash Programming

Regardless of the method used, all programming of Flash memory is done with the table read and table write instructions. These allow direct read and write access to the program memory space from the data memory while the device is in normal operating mode. The 24-bit target address in the program memory is formed using bits <7:0> of the TBLPAG register and the Effective Address (EA) from a W register specified in the table instruction, as shown in Figure 5-1.

The TBLRDL and the TBLWTL instructions are used to read or write to the bits<15:0> of program memory. TBLRDL and TBLWTL can access program memory in both Word and Byte modes.

The TBLRDH and TBLWTH instructions are used to read or write to bits<23:16> of program memory. TBLRDH and TBLWTH can also access program memory in Word or Byte mode.

FIGURE 5-1: ADDRESSING FOR TABLE REGISTERS



8.3 Oscillator Control Registers

REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER(1,3)

U-0	R-0	R-0	R-0	U-0	R/W-y	R/W-y	R/W-y
—	COSC<2:0>			—	NOSC<2:0>(2)		
bit 15							bit 8

R/W-0	R/W-0	R-0	U-0	R/C-0	U-0	R/W-0	R/W-0
CLKLOCK	IOLOCK	LOCK	—	CF	—	LPOSCEN	OSWEN
bit 7							bit 0

Legend:	y = Value set from Configuration bits on POR		C = Clear only bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **COSC<2:0>:** Current Oscillator Selection bits (read-only)
111 = Fast RC oscillator (FRC) with Divide-by-n
110 = Fast RC oscillator (FRC) with Divide-by-16
101 = Low-Power RC oscillator (LPRC)
100 = Secondary oscillator (Sosc)
011 = Primary oscillator (XT, HS, EC) with PLL
010 = Primary oscillator (XT, HS, EC)
001 = Fast RC oscillator (FRC) with PLL
000 = Fast RC oscillator (FRC)

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **NOSC<2:0>:** New Oscillator Selection bits(2)
111 = Fast RC oscillator (FRC) with Divide-by-n
110 = Fast RC oscillator (FRC) with Divide-by-16
101 = Low-Power RC oscillator (LPRC)
100 = Secondary oscillator (Sosc)
011 = Primary oscillator (XT, HS, EC) with PLL
010 = Primary oscillator (XT, HS, EC)
001 = Fast RC oscillator (FRC) with PLL
000 = Fast RC oscillator (FRC)

bit 7 **CLKLOCK:** Clock Lock Enable bit
If clock switching is enabled and FSCM is disabled (FOSC<FCKSM> = 0b01)
1 = Clock switching is disabled, system clock source is locked
0 = Clock switching is enabled, system clock source can be modified by clock switching

bit 6 **IOLOCK:** Peripheral Pin Select Lock bit
1 = Peripherial Pin Select is locked, write to peripheral pin select register is not allowed
0 = Peripherial Pin Select is unlocked, write to peripheral pin select register is allowed

bit 5 **LOCK:** PLL Lock Status bit (read-only)
1 = Indicates that PLL is in lock, or PLL start-up timer is satisfied
0 = Indicates that PLL is out of lock, start-up timer is in progress or PLL is disabled

bit 4 **Unimplemented:** Read as '0'

Note 1: Writes to this register require an unlock sequence. Refer to **Section 7. "Oscillator"** (DS70186) in the *"dsPIC33F/PIC24H Family Reference Manual"* for details.

2: Direct clock switches between any primary oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transition clock source between the two PLL modes.

3: This register is reset only on a Power-on Reset (POR).

9.2.2 IDLE MODE

The following occur in Idle mode:

- The CPU stops executing instructions
- The WDT is automatically cleared
- The system clock source remains active. By default, all peripheral modules continue to operate normally from the system clock source, but can also be selectively disabled (see **Section 9.4 "Peripheral Module Disable"**).
- If the WDT or FSCM is enabled, the LPRC also remains active

The device will wake from Idle mode on any of these events:

- Any interrupt that is individually enabled
- Any device Reset
- A WDT time-out

On wake-up from Idle mode, the clock is reapplied to the CPU and instruction execution will begin (2-4 cycles later), starting with the instruction following the PWRSAV instruction, or the first instruction in the ISR.

9.2.3 INTERRUPTS COINCIDENT WITH POWER SAVE INSTRUCTIONS

Any interrupt that coincides with the execution of a PWRSAV instruction is held off until entry into Sleep or Idle mode is completed. The device then wakes up from Sleep or Idle mode.

9.3 Doze Mode

The preferred strategies for reducing power consumption are changing clock speed and invoking one of the power-saving modes. In some circumstances, however, these are not practical. For example, it may be necessary for an application to maintain uninterrupted synchronous communication, even while it is doing nothing else. Reducing system clock speed can introduce communication errors, while using a power-saving mode can stop communications completely.

Doze mode is a simple and effective alternative method to reduce power consumption while the device is still executing code. In this mode, the system clock continues to operate from the same source and at the same speed. Peripheral modules continue to be clocked at the same speed, while the CPU clock speed is reduced. Synchronization between the two clock domains is maintained, allowing the peripherals to access the SFRs while the CPU executes code at a slower rate.

Doze mode is enabled by setting the DOZEN bit (CLKDIV<11>). The ratio between peripheral and core clock speed is determined by the DOZE<2:0> bits (CLKDIV<14:12>). There are eight possible configurations, from 1:1 to 1:128, with 1:1 being the default setting.

Programs can use Doze mode to selectively reduce power consumption in event-driven applications. This allows clock-sensitive functions, such as synchronous communications, to continue without interruption while the CPU idles, waiting for something to invoke an interrupt routine. An automatic return to full-speed CPU operation on interrupts can be enabled by setting the ROI bit (CLKDIV<15>). By default, interrupt events have no effect on Doze mode operation.

For example, suppose the device is operating at 20 MIPS and the CAN module has been configured for 500 kbps based on this device operating speed. If the device is placed in Doze mode with a clock frequency ratio of 1:4, the CAN module continues to communicate at the required bit rate of 500 kbps, but the CPU now starts executing instructions at a frequency of 5 MIPS.

9.4 Peripheral Module Disable

The Peripheral Module Disable (PMD) registers provide a method to disable a peripheral module by stopping all clock sources supplied to that module. When a peripheral is disabled using the appropriate PMD control bit, the peripheral is in a minimum power consumption state. The control and status registers associated with the peripheral are also disabled. So writes to those registers will have no effect and read values will be invalid.

A peripheral module is enabled only if both the associated bit in the PMD register are cleared and the peripheral is supported by the specific PIC24H variant. If the peripheral is present in the device, it is enabled in the PMD register by default.

Note:	If a PMD bit is set, the corresponding module is disabled after a delay of one instruction cycle. Similarly, if a PMD bit is cleared, the corresponding module is enabled after a delay of one instruction cycle (assuming the module control registers are already configured to enable module operation).

10.2 Open-Drain Configuration

In addition to the PORT, LAT and TRIS registers for data control, some port pins can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs higher than VDD (e.g., 5V) on any desired 5V tolerant pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum VIH specification.

See the **"Pin Diagrams"** section for the available pins and their functionality.

10.3 Configuring Analog Port Pins

The AD1PCFG and TRIS registers control the operation of the Analog-to-Digital (A/D) port pins. The port pins that are desired as analog inputs must have their corresponding TRIS bit set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The AD1PCFGL register has a default value of 0x0000; therefore, all pins that share ANx functions are analog (not digital) by default.

When the PORT register is read, all pins configured as analog input channels will read as cleared (a low level).

Pins configured as digital inputs will not convert an analog input. Analog levels on any pin that is defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

10.4 I/O Port Write/Read Timing

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically this instruction would be a NOP. Examples are shown in Example 10-1 and Example 10-2. This also applies to PORT bit operations, such as `BSET PORTB, # RB0`, which are single cycle read-modify-write. All PORT bit operations, such as `MOV PORTB, W0` or `BSET PORTB, # RBx`, read the pin and *not* the latch.

10.5 Input Change Notification

The input change notification function of the I/O ports allows the PIC24HJ32GP202/204 and PIC24HJ16GP304 devices to generate interrupt requests to the processor in response to a change-of-state on selected input pins. This feature can detect input change-of-states even in Sleep mode, when the clocks are disabled. Depending on the device pin count, up to 31 external signals (CNx pin) can be selected (enabled) for generating an interrupt request on a change-of-state.

Four control registers are associated with the CN module. The CNEN1 and CNEN2 registers contain the interrupt enable control bits for each of the CN input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

Each CN pin also has a weak pull-up connected to it. The pull-ups act as a current source connected to the pin, and eliminate the need for external resistors when push button or keypad devices are connected. The pull-ups are enabled separately using the CNPU1 and CNPU2 registers, which contain the control bits for each of the CN pins. Setting any of the control bits enables the weak pull-ups for the corresponding pins.

Note:	Pull-ups on change notification pins should always be disabled when the port pin is configured as a digital output.

EXAMPLE 10-1: PORT WRITE/READ EXAMPLE

```
MOV     0xFF00, W0          ; Configure PORTB<15:8> as inputs
MOV     W0, TRISBB          ; and PORTB<7:0> as outputs
NOP                         ; Delay 1 cycle
btss    PORTB, #13          ; Next Instruction
```

EXAMPLE 10-2: PORT BIT OPERATIONS

```
Incorrect:
BSET    PORTB, #RB1         ;Set PORTB<RB1> high
BSET    PORTB, #RB6         ;Set PORTB<RB6> high

Correct:
BSET    PORTB, #RB1         ;Set PORTB<RB1> high
NOP
BSET    PORTB, #RB6         ;Set PORTB<RB6> high
NOP

Preferred:
BSET    LATB, LATB1         ;Set PORTB<RB1> high
BSET    LATB, LATB6         ;Set PORTB<RB6> high
```

13.2 Input Capture Registers

REGISTER 13-1: ICxCON: INPUT CAPTURE x CONTROL REGISTER

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	ICSIDL	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R-0, HC	R-0, HC	R/W-0	R/W-0	R/W-0
ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>		
bit 7							bit 0

Legend:		HC = Cleared in Hardware	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **ICSIDL:** Input Capture Module Stop in Idle Control bit
1 = Input capture module will halt in CPU Idle mode
0 = Input capture module will continue to operate in CPU Idle mode

bit 12-8 **Unimplemented:** Read as '0'

bit 7 **ICTMR:** Input Capture Timer Select bits
1 = TMR2 contents are captured on capture event
0 = TMR3 contents are captured on capture event

bit 6-5 **ICI<1:0>:** Select Number of Captures per Interrupt bits
11 = Interrupt on every fourth capture event
10 = Interrupt on every third capture event
01 = Interrupt on every second capture event
00 = Interrupt on every capture event

bit 4 **ICOV:** Input Capture Overflow Status Flag bit (read-only)
1 = Input capture overflow occurred
0 = No input capture overflow occurred

bit 3 **ICBNE:** Input Capture Buffer Empty Status bit (read-only)
1 = Input capture buffer is not empty, at least one more capture value can be read
0 = Input capture buffer is empty

bit 2-0 **ICM<2:0>:** Input Capture Mode Select bits
111 = Input capture functions as interrupt pin only when device is in Sleep or Idle mode
(Rising edge detect only, all other control bits are not applicable.)
110 = Unused (module disabled)
101 = Capture mode, every 16th rising edge
100 = Capture mode, every 4th rising edge
011 = Capture mode, every rising edge
010 = Capture mode, every falling edge
001 = Capture mode, every edge (rising and falling)
(ICI<1:0> bits do not control interrupt generation for this mode.)
000 = Input capture module turned off

TABLE 20-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
47	RCALL	RCALL Expr	Relative Call	1	2	None
		RCALL Wn	Computed Call	1	2	None
48	REPEAT	REPEAT #lit14	Repeat Next Instruction lit14 + 1 times	1	1	None
		REPEAT Wn	Repeat Next Instruction (Wn) + 1 times	1	1	None
49	RESET	RESET	Software device Reset	1	1	None
50	RETFIE	RETFIE	Return from interrupt	1	3 (2)	None
51	RETLW	RETLW #lit10,Wn	Return with literal in Wn	1	3 (2)	None
52	RETURN	RETURN	Return from Subroutine	1	3 (2)	None
53	RLC	RLC f	f = Rotate Left through Carry f	1	1	C,N,Z
		RLC f,WREG	WREG = Rotate Left through Carry f	1	1	C,N,Z
		RLC Ws,Wd	Wd = Rotate Left through Carry Ws	1	1	C,N,Z
54	RLNC	RLNC f	f = Rotate Left (No Carry) f	1	1	N,Z
		RLNC f,WREG	WREG = Rotate Left (No Carry) f	1	1	N,Z
		RLNC Ws,Wd	Wd = Rotate Left (No Carry) Ws	1	1	N,Z
55	RRC	RRC f	f = Rotate Right through Carry f	1	1	C,N,Z
		RRC f,WREG	WREG = Rotate Right through Carry f	1	1	C,N,Z
		RRC Ws,Wd	Wd = Rotate Right through Carry Ws	1	1	C,N,Z
56	RRNC	RRNC f	f = Rotate Right (No Carry) f	1	1	N,Z
		RRNC f,WREG	WREG = Rotate Right (No Carry) f	1	1	N,Z
		RRNC Ws,Wd	Wd = Rotate Right (No Carry) Ws	1	1	N,Z
57	SE	SE Ws,Wnd	Wnd = sign-extended Ws	1	1	C,N,Z
58	SETM	SETM f	f = 0xFFFF	1	1	None
		SETM WREG	WREG = 0xFFFF	1	1	None
		SETM Ws	Ws = 0xFFFF	1	1	None
59	SL	SL f	f = Left Shift f	1	1	C,N,OV,Z
		SL f,WREG	WREG = Left Shift f	1	1	C,N,OV,Z
		SL Ws,Wd	Wd = Left Shift Ws	1	1	C,N,OV,Z
		SL Wb,Wns,Wnd	Wnd = Left Shift Wb by Wns	1	1	N,Z
		SL Wb,#lit5,Wnd	Wnd = Left Shift Wb by lit5	1	1	N,Z
60	SUB	SUB f	f = f - WREG	1	1	C,DC,N,OV,Z
		SUB f,WREG	WREG = f - WREG	1	1	C,DC,N,OV,Z
		SUB #lit10,Wn	Wn = Wn - lit10	1	1	C,DC,N,OV,Z
		SUB Wb,Ws,Wd	Wd = Wb - Ws	1	1	C,DC,N,OV,Z
		SUB Wb,#lit5,Wd	Wd = Wb - lit5	1	1	C,DC,N,OV,Z
61	SUBB	SUBB f	f = f - WREG - ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB f,WREG	WREG = f - WREG - ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB #lit10,Wn	Wn = Wn - lit10 - ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB Wb,Ws,Wd	Wd = Wb - Ws - ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB Wb,#lit5,Wd	Wd = Wb - lit5 - ($\overline{C}$)	1	1	C,DC,N,OV,Z
62	SUBR	SUBR f	f = WREG - f	1	1	C,DC,N,OV,Z
		SUBR f,WREG	WREG = WREG - f	1	1	C,DC,N,OV,Z
		SUBR Wb,Ws,Wd	Wd = Ws - Wb	1	1	C,DC,N,OV,Z
		SUBR Wb,#lit5,Wd	Wd = lit5 - Wb	1	1	C,DC,N,OV,Z
63	SUBBR	SUBBR f	f = WREG - f - ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBBR f,WREG	WREG = WREG - f - ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBBR Wb,Ws,Wd	Wd = Ws - Wb - ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBBR Wb,#lit5,Wd	Wd = lit5 - Wb - ($\overline{C}$)	1	1	C,DC,N,OV,Z
64	SWAP	SWAP.b Wn	Wn = nibble swap Wn	1	1	None
		SWAP Wn	Wn = byte swap Wn	1	1	None
65	TBLRDH	TBLRDH Ws,Wd	Read Prog<23:16> to Wd<7:0>	1	2	None

21.2 MPLAB C Compilers for Various Device Families

The MPLAB C Compiler code development systems are complete ANSI C compilers for Microchip's PIC18, PIC24 and PIC32 families of microcontrollers and the dsPIC30 and dsPIC33 families of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

21.3 HI-TECH C for Various Device Families

The HI-TECH C Compiler code development systems are complete ANSI C compilers for Microchip's PIC family of microcontrollers and the dsPIC family of digital signal controllers. These compilers provide powerful integration capabilities, omniscient code generation and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

The compilers include a macro assembler, linker, preprocessor, and one-step driver, and can run on multiple platforms.

21.4 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

21.5 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

21.6 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC devices. MPLAB C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command line interface
- Rich directive set
- Flexible macro language
- MPLAB IDE compatibility

22.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of PIC24HJ32GP202/204 and PIC24HJ16GP304 electrical characteristics. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the PIC24HJ32GP202/204 and PIC24HJ16GP304 family are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +160°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to V_{SS}(4) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when V_{DD} < 3.0V(4) ..... -0.3V to 3.6V
Voltage on any 5V tolerant pin with respect to Vss when $V_{DD} \geq 3.0V$(4) ..... -0.3V to +5.6V
Maximum current out of V_{SS} pin ..... 300 mA
Maximum current into V_{DD} pin(2) ..... 250 mA
Maximum current sourced/sunk by any 2x I/O pin(3) ..... 8 mA
Maximum current sourced/sunk by any 4x I/O pin(3) ..... 15 mA
Maximum current sourced/sunk by any 8x I/O pin(3) ..... 25 mA
Maximum current sunk by all ports ..... 200 mA
Maximum current sourced by all ports(2) ..... 200 mA

Note 1: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 22-2).

3: Exceptions are CLKOUT, which is able to sink/source 25 mA, and the V_{REF}+, V_{REF}-, SCLx, SDAx, PGECx and PGEDx pins, which are able to sink/source 12 mA.

4: Refer to the **"Pin Diagrams"** section for 5V tolerant pins.

TABLE 22-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.(3)	**Typical(2)**	**Max**	**Units**	**Conditions**		
Power-Down Current (I_{PD})(1)						
DC60d	55	500	μA	-40°C	3.3V	Base Power-Down Current(3,4)
DC60a	63	300	μA	+25°C		
DC60b	85	350	μA	+85°C		
DC60c	146	600	μA	+125°C		
DC61d	8	15	μA	-40°C	3.3V	Watchdog Timer Current: ΔI_{WDT}(3,5)
DC61a	2	3	μA	+25°C		
DC61b	2	2	μA	+85°C		
DC61c	3	5	μA	+125°C		

Note 1: I_{PD} (Sleep) current is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration word
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}, WDT and FSCM are disabled, all peripheral modules are disabled (PMDx bits are all ones)
- VREGS bit (RCON<8>) = 0 (i.e., core regulator is set to stand-by while the device is in Sleep mode)
- RTCC is disabled.
- The VREGSF bit (RCON<11>) = 0 (i.e., Flash regulator is set to stand-by while the device is in Sleep mode)
- JTAG is disabled

2: Data in the "Typ" column is at 3.3V, +25ºC unless otherwise stated.

3: The Watchdog Timer Current is the additional current consumed when the WDT module is enabled. This current should be added to the base I_{PD} current.

4: These currents are measured on the device containing the most memory in this family.

5: These parameters are characterized, but are not tested in manufacturing.

FIGURE 22-2: EXTERNAL CLOCK TIMING

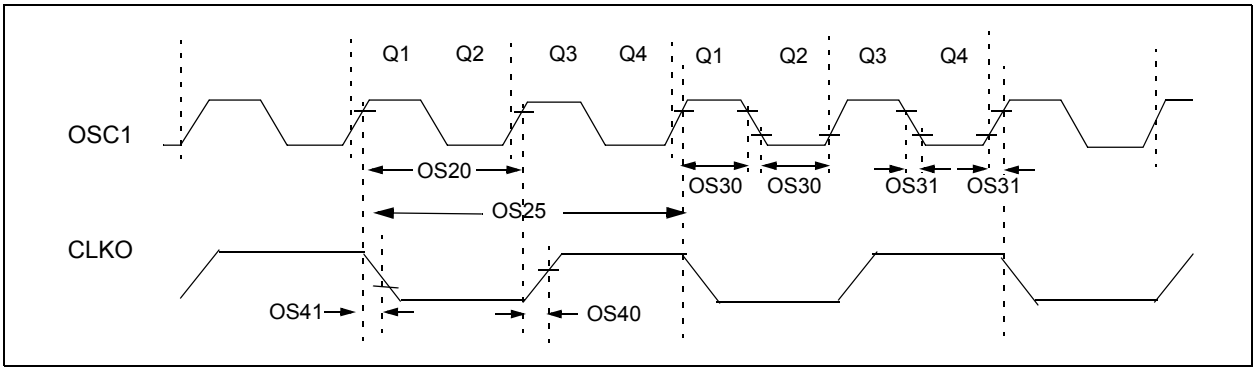


TABLE 22-16: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symb**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
OS10	FIN	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)(4)	DC	—	40	MHz	EC
		Oscillator Crystal Frequency(5)	3.5 10	— —	10 40	MHz MHz	XT HS
				—	33	kHz	SOSC
OS20	TOSC	TOSC = 1/FOSC(4)	12.5	—	DC	ns	—
OS25	TCY	Instruction Cycle Time(2,4)	25	—	DC	ns	—
OS30	TosL, TosH	External Clock in (OSC1)(5) High or Low Time	0.375 x TOSC	—	0.625 x TOSC	ns	EC
OS31	TosR, TosF	External Clock in (OSC1)(5) Rise or Fall Time	—	—	20	ns	EC
OS40	TckR	CLKO Rise Time(3,5)	—	5.2	—	ns	—
OS41	TckF	CLKO Fall Time(3,5)	—	5.2	—	ns	—
OS42	GM	External Oscillator Transconductance(6)	14	16	18	mA/V	VDD = 3.3V TA = +25ºC

Note 1: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated.

2: Instruction cycle period (TCY) equals two times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits can result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at “min.” values with an external clock applied to the OSC1/CLKI pin. When an external clock input is used, the “max.” cycle time limit is “DC” (no clock) for all devices.

3: Measurements are taken in EC mode. The CLKO signal is measured on the OSC2 pin.

4: These parameters are characterized by similarity, but are tested in manufacturing at FIN = 40 MHz only.

5: These parameters are characterized by similarity, but are not tested in manufacturing.

6: Data for this parameter is preliminary. This parameter is characterized, but is not tested in manufacturing.

TABLE 22-21: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER TIMING REQUIREMENTS

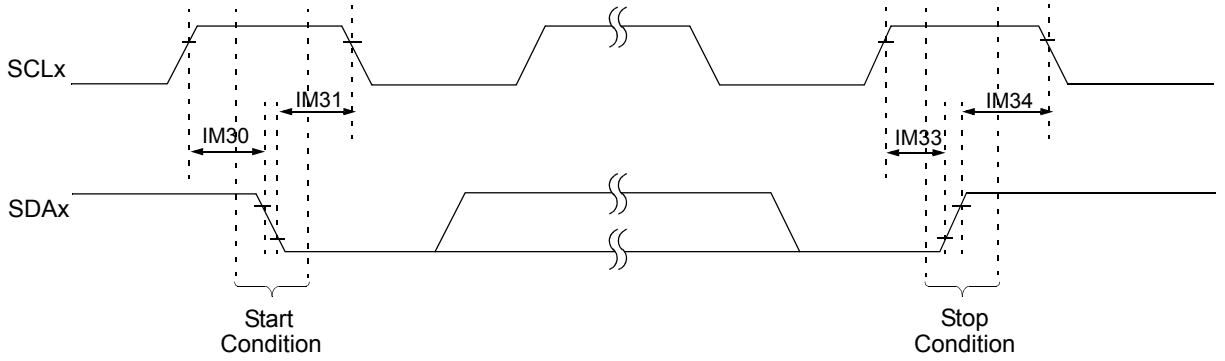
AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SY10	TMCL	$\overline{\text{MCLR}}$ Pulse-Width (low)(1)	2	—	—	μs	-40°C to +85°C
SY11	TPWRT	Power-up Timer Period(1)	—	2 4 8 16 32 64 128	—	ms	-40°C to +85°C User programmable
SY12	TPOR	Power-on Reset Delay(3)	3	10	30	μs	-40°C to +85°C
SY13	TIOZ	I/O High-Impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset(1)	0.68	0.72	1.2	μs	—
SY20	TWDT1	Watchdog Timer Time-out Period(1)	—	—	—	ms	See **Section 19.4 "Watchdog Timer (WDT)"** and LPRC specification F21a (Table 22-19).
SY30	TOST	Oscillator Start-up Time	—	1024 TOSC	—	—	TOSC = OSC1 period
SY35	TFSCM	Fail-Safe Clock Monitor Delay(1)	—	500	900	μs	-40°C to +85°C

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

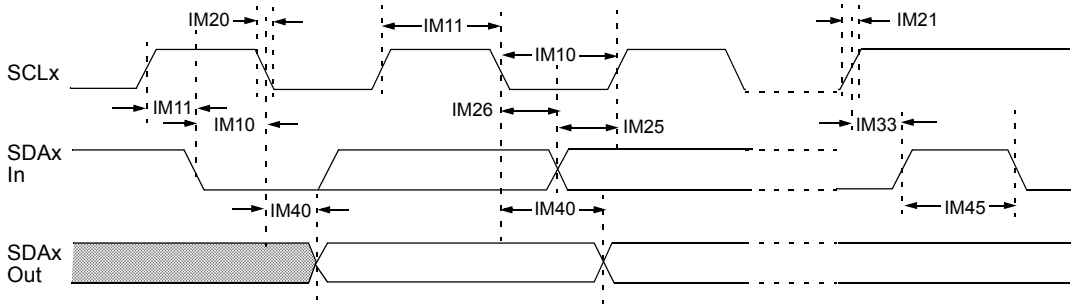
3: These parameters are characterized by similarity, but are not tested in manufacturing.

FIGURE 22-17: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)



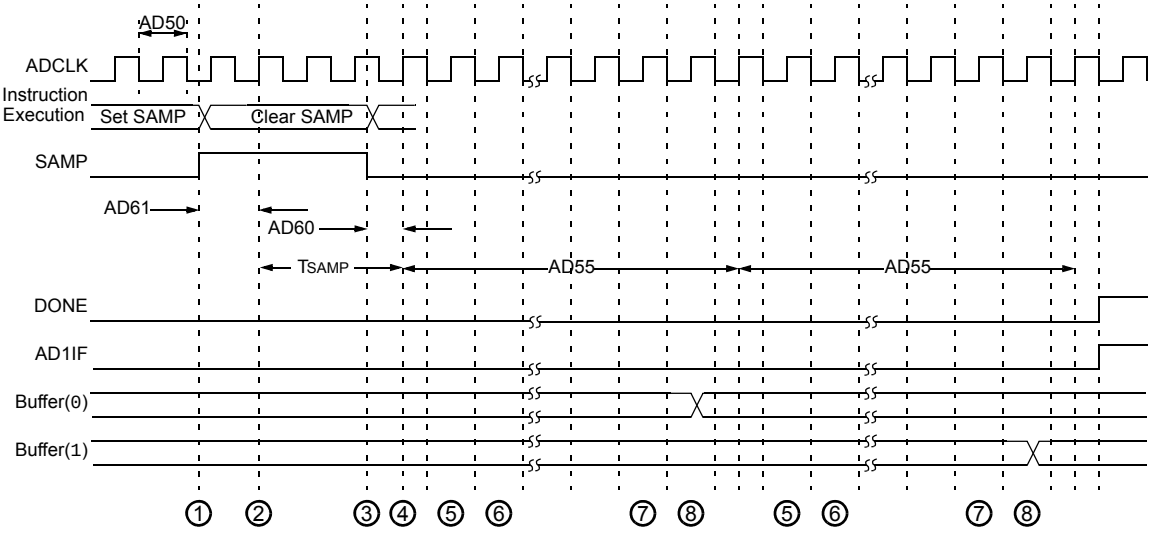
Note: Refer to Figure 22-1 for load conditions.

FIGURE 22-18: I2Cx BUS DATA TIMING CHARACTERISTICS (MASTER MODE)



Note: Refer to Figure 22-1 for load conditions.

FIGURE 22-22: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000)



(1) – Software sets AD1CON. SAMP to start sampling.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70183) in the *"dsPIC33F/PIC24H Family Reference Manual"*.

(3) – Software clears AD1CON. SAMP to start conversion.

(4) – Sampling ends, conversion sequence starts.

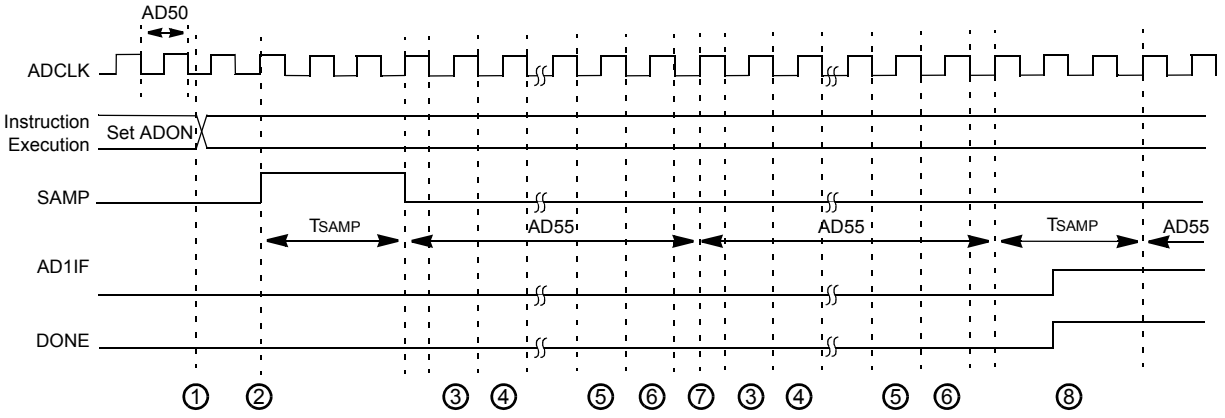
(5) – Convert bit 9.

(6) – Convert bit 8.

(7) – Convert bit 0.

(8) – One TAD for end of conversion.

FIGURE 22-23: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



(1) – Software sets AD1CON. ADON to start AD operation.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70183) in the *"dsPIC33F/PIC24H Family Reference Manual"*.

(3) – Convert bit 9.

(4) – Convert bit 8.

(5) – Convert bit 0.

(6) – One TAD for end of conversion.

(7) – Begin conversion of next channel.

(8) – Sample for time specified by SAMC<4:0>.

23.2 AC Characteristics and Timing Parameters

The information contained in this section defines PIC24HJ32GP202/204 and PIC24HJ16GP304 AC characteristics and timing parameters for high temperature devices. However, all AC timing specifications in this section are the same as those in **Section 22.2 "AC Characteristics and Timing Parameters"**, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, parameter OS53 in **Section 22.2 "AC Characteristics and Timing Parameters"** is the Industrial and Extended temperature equivalent of HOS53.

TABLE 23-8: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature Operating voltage VDD range as described in Table 23-1.

FIGURE 23-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

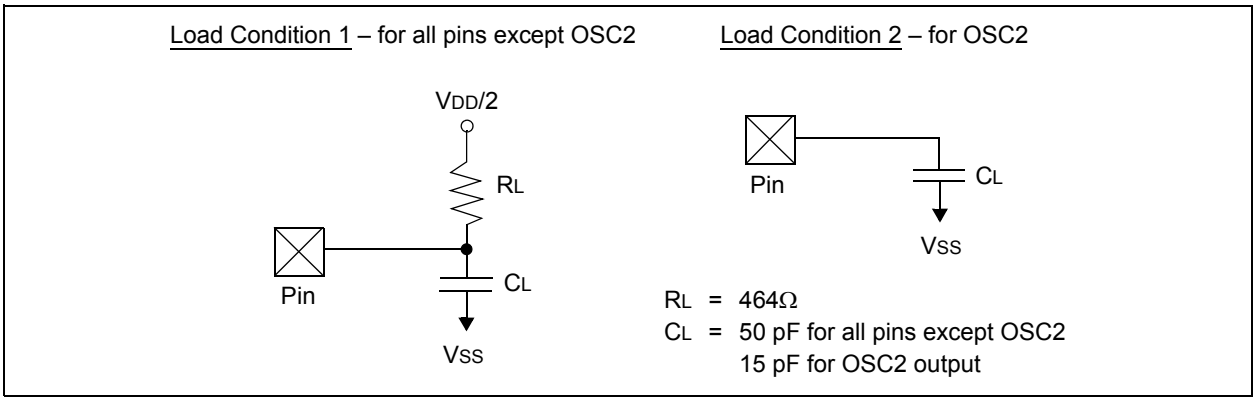


TABLE 23-9: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS		**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
HOS53	DCLK	CLKO Stability (Jitter)(1)	-5	0.5	5	%	Measured over 100 ms period

Note 1: These parameters are characterized by similarity, but are not tested in manufacturing. This specification is based on clock cycle by clock cycle measurements. To calculate the effective jitter for individual time bases or communication clocks use this formula:

$$Peripheral\ Clock\ Jitter = \frac{DCLK}{\sqrt{\left(\frac{FOSC}{Peripheral\ Bit\ Rate\ Clock}\right)}}$$

For example: Fosc = 32 MHz, DCLK = 5%, SPI bit rate clock, (i.e., SCK) is 2 MHz.

$$SPI\ SCK\ Jitter = \left[\frac{DCLK}{\sqrt{\left(\frac{32\ MHz}{2\ MHz}\right)}}\right] = \left[\frac{5\%}{\sqrt{16}}\right] = \left[\frac{5\%}{4}\right] = 1.25\%$$

TABLE 23-18: ADC CONVERSION (12-BIT MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
Clock Parameters							
HAD50	TAD	ADC Clock Period(1)	147	—	—	ns	—
Conversion Rate							
HAD56	FCNV	Throughput Rate(1)	—	—	400	Ksps	—

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 23-19: ADC CONVERSION (10-BIT MODE) TIMING REQUIREMENTS

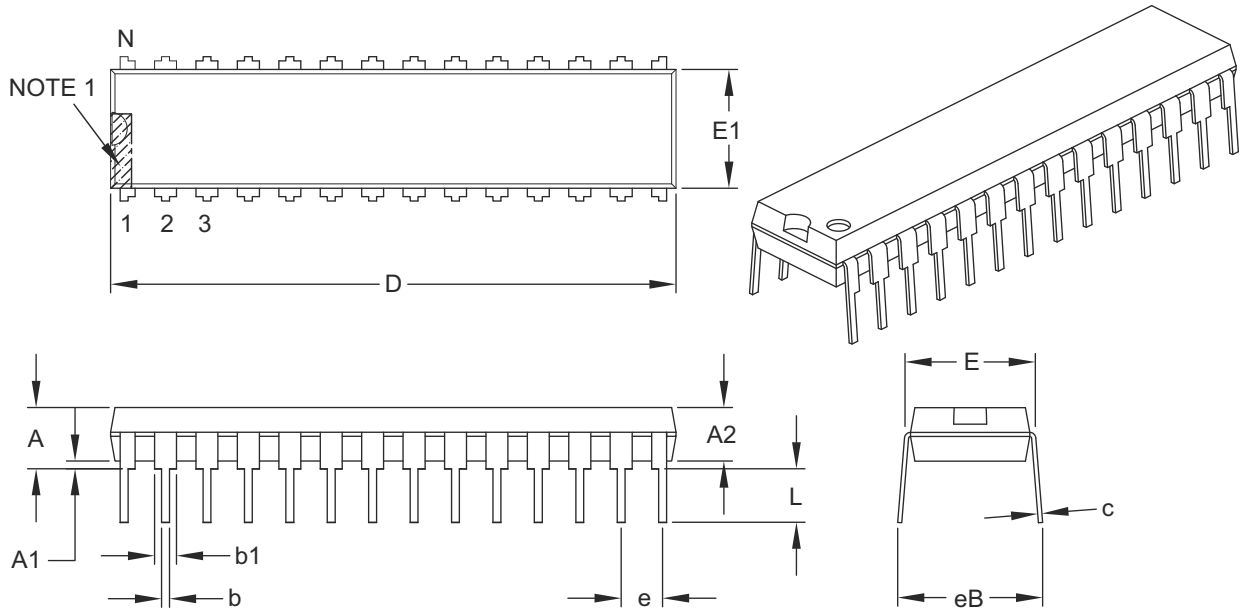
AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
Clock Parameters							
HAD50	TAD	ADC Clock Period(1)	104	—	—	ns	—
Conversion Rate							
HAD56	FCNV	Throughput Rate(1)	—	—	800	Ksps	—

Note 1: These parameters are characterized but not tested in manufacturing.

25.2 Package Details

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (July 2007)

Initial release of this document.

Revision B (June 2008)

This revision includes minor typographical and formatting changes throughout the data sheet text.

The major changes are referenced by their respective section in the following table.

TABLE 25-1: MAJOR SECTION UPDATES

Section Name	Update Description
"High-Performance, 16-bit Microcontrollers"	Added Extended Interrupts column to Remappable Peripherals in the Controller Families table and Note 2 (see Table 1). Added Note 1 to all pin diagrams, which references RPn pin usage by remappable peripherals (see **"Pin Diagrams"**).
Section 1.0 "Device Overview"	Changed PORTA pin name from RA15 to RA10 (see Table 1-1).
Section 3.0 "Memory Organization"	Updated Reset values for the following SFRs: IPC1, IPC3-IPC5, IPC7, IPC16, and INTTREG (see Table 3-4). Added the System Control Register Map (see Table 3-20).
Section 5.0 "Resets"	Entire section was replaced to maintain consistency with other PIC24H data sheets.
Section 7.0 "Oscillator Configuration"	Removed the first sentence of the third clock source item (External Clock) in **Section 7.1.1.2 "Primary"**. Updated the default bit values for DOZE and FRCDIV in the Clock Divisor Register (see Register 7-2). Added the center frequency in the OSCTUN register for the FRC Tuning bits (TUN<5:0>) value `011111` and updated the center frequency for bits value `011110` (see Register 7-4).
Section 8.0 "Power-Saving Features"	Added the following two registers: • PMD1: Peripheral Module Disable Control Register 1 • PMD2: Peripheral Module Disable Control Register 2
Section 9.0 "I/O Ports"	Added paragraph and Table 9-1 to **Section 9.1.1 "Open-Drain Configuration"**, which provides details on I/O pins and their functionality. Removed the following sections, which are now available in the related section of the dsPIC33F/PIC24H Family Reference Manual: • 9.4.2 "Available Peripherals" • 9.4.3.3 "Mapping" • 9.4.5 "Considerations for Peripheral Pin Selection"
Section 13.0 "Output Compare"	Replaced sections 13.1, 13.2 and 13.3 and related figures and tables with entirely new content.
Section 14.0 "Serial Peripheral Interface (SPI)"	Removed the following sections, which are now available in the related section of the dsPIC33F/PIC24H Family Reference Manual: • 14.1 "Interrupts" • 14.2 "Receive Operations" • 14.3 "Transmit Operations" • 14.4 "SPI Setup" (retained Figure 14-1: SPI Module Block Diagram)